

ABSTRACT

PROTECTIVE TAPE ATTACHING METHOD AND PROTECTIVE TAPE ATTACHING APPARATUS

Disclosed herein is a protective tape attaching method for attaching a protective tape to a wafer, the protective tape having a size corresponding to the size of the wafer. The protective tape attaching method includes: a bending step of bending a release paper to which an adhesive layer of the protective tape is previously attached, stretching the release paper to peel a front end portion of the protective tape from the release paper, and attaching the front end portion of the protective tape to the wafer; and an attaching step of pressing the other side of the protective tape opposite to the adhesive layer by using a pressure roller to thereby bring the adhesive layer of the protective tape into close contact with the wafer after performing the bending step.

(Figure 1)